

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
LIN-CHEN HO	02/21/2017
WEI-WEN TSAI	02/21/2017
CHENG-PING LEE	02/20/2017
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15815292
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<b>NAME OF SUBMITTER:</b>	PATRICIA A. CONNELL
<b>SIGNATURE:</b>	/Patricia A. Connell/
<b>DATE SIGNED:</b>	01/12/2018
<b>Total Attachments: 1</b>	
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ASSIGNMENT OF PATENT APPLICATION

We/I, the undersigned

Lin-Chen Ho, of Taichung, Taiwan; Wei-Wen Tsai, of Philadelphia, Pennsylvania and Cheng-Ping Lee of Miaoli County, Taiwan

Hereby declare that

We/I are true and first inventor(s) of an invention relating to

CHEMICAL MECHANICAL POLISHING METHOD FOR TUNGSTEN USING POLYGLYCOLS AND POLYGLYCOL DERIVATIVES

which is disclosed in an application for Letters Patent in the United States of America, executed the <sup>20th</sup> day of ~~February~~ <sup>Feb</sup>, 2017 (Case No. 80250); and, for valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby sell, assign and transfer unto Rohm and Haas Electronic Materials CMP Holdings, Inc., a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its mailing address at 451 Bellevue Road, Newark, Delaware, hereinafter referred to as the assignee, the entire right, title, and interest in and to the aforesaid application for Letters Patent, including any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, and the entire right, title and interest in and to any and all our inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, and in and to any and all applications for letters Patent for any such inventions in any country whatsoever, and in and to any and all patents for any such inventions in any country whatsoever, with the sole right to file such applications in its name or ours, including the sole right to file such applications under the aforesaid International Convention, together with the sole right to have said patents granted in its name or ours and to enforce said patents and to sue for and recover profits and damages for any and all infringements thereof, and hereby agree, whenever requested, to communicate to us respecting said inventions, to testify in any legal proceeding, to execute all applications, papers, or instruments necessary or required by said assignee, its successors, assigns, and legal representatives to carry into effect any of the provisions of this instrument, and generally to do everything possible to aid said assignee, its successors, assigns and legal representatives to obtain and enforce proper patent protection for said inventions in any and all countries.

IN WITNESS WHEREOF, We have hereunto signed our names on the day and year set forth below.

Lin-Chen Ho  
Lin-Chen Ho

2/21/2017  
DATE

Wei-Wen Tsai  
Wei-Wen Tsai

2/21/2017  
DATE

Cheng-Ping Lee  
Cheng-Ping Lee

2/20/2017  
DATE